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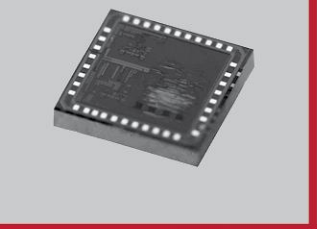
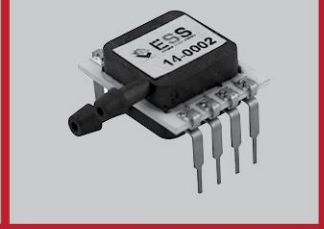

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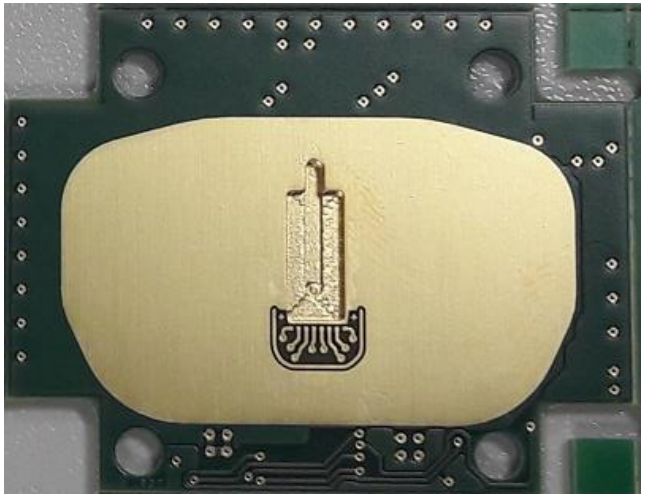
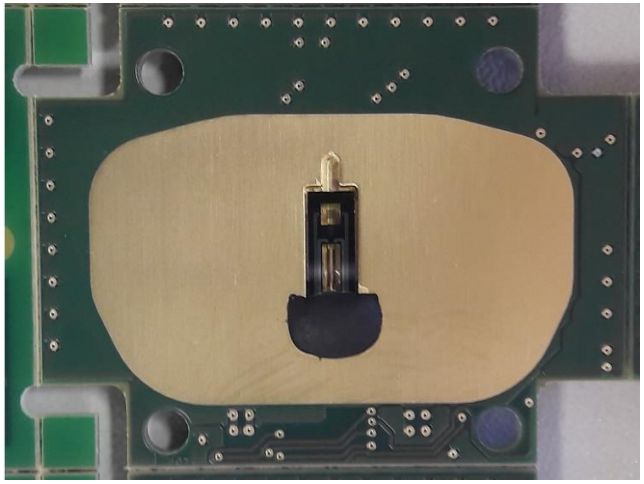
ESF Assembly Information

Strictly Confidential Information

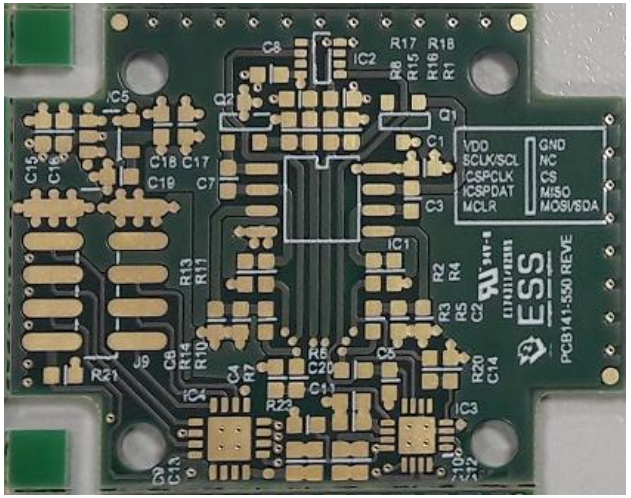
The final product

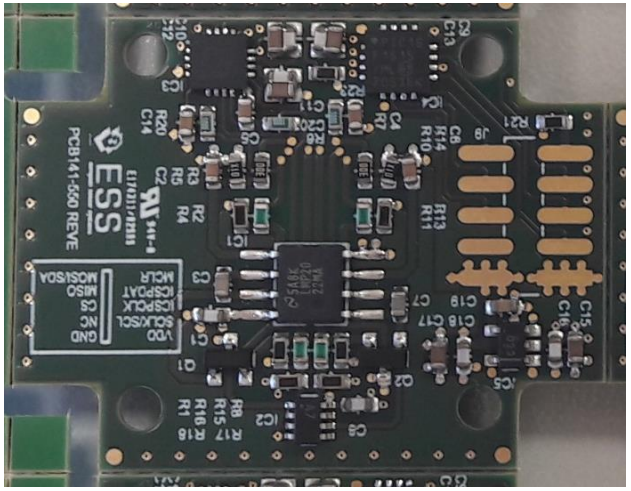
Flow Sensor PCB





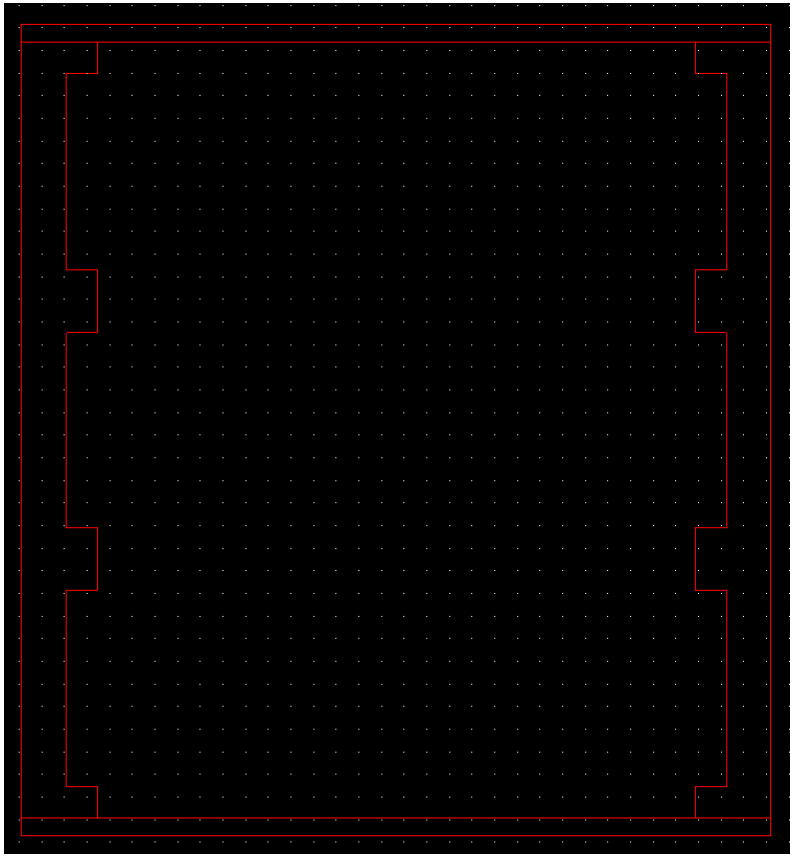
MEMS Side





Electronics Components Side

Panel Information



ESF-200-B PANEL MATERIAL : FR4

TYPE: FOUR LAYER PCB

PCBS / PANEL: 6

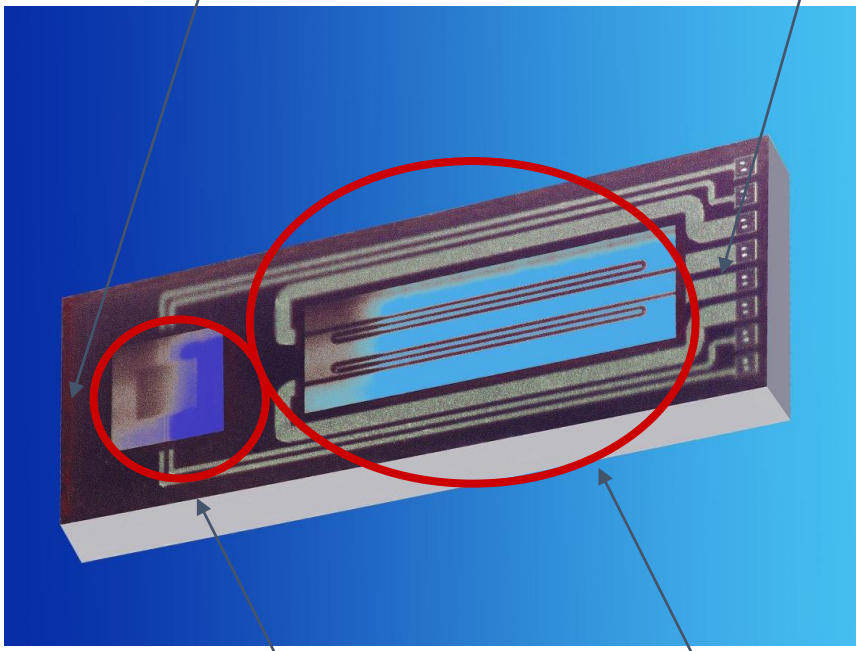
PANEL DIMENSIONS: 83.9 x 91.1 mm

PANEL ROUTING : TAB ROUTING

DELIVERY METHOD: IN HUMIDITY SEALED PACKAGE

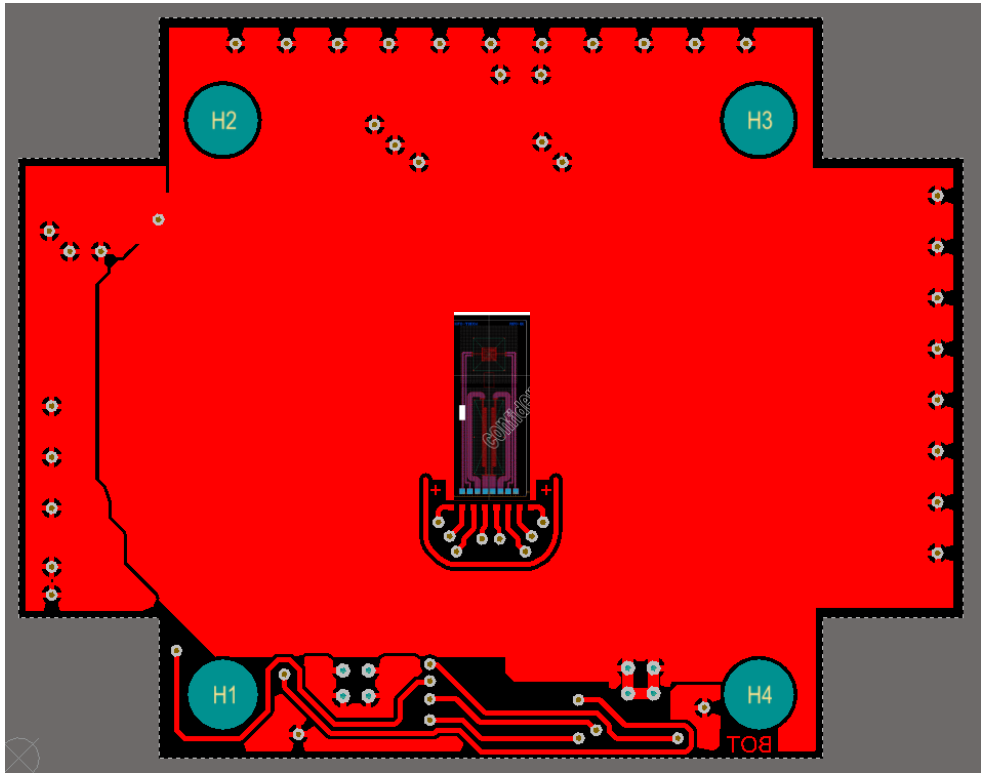
MEMS die information

Pick Up Tool Handling Points



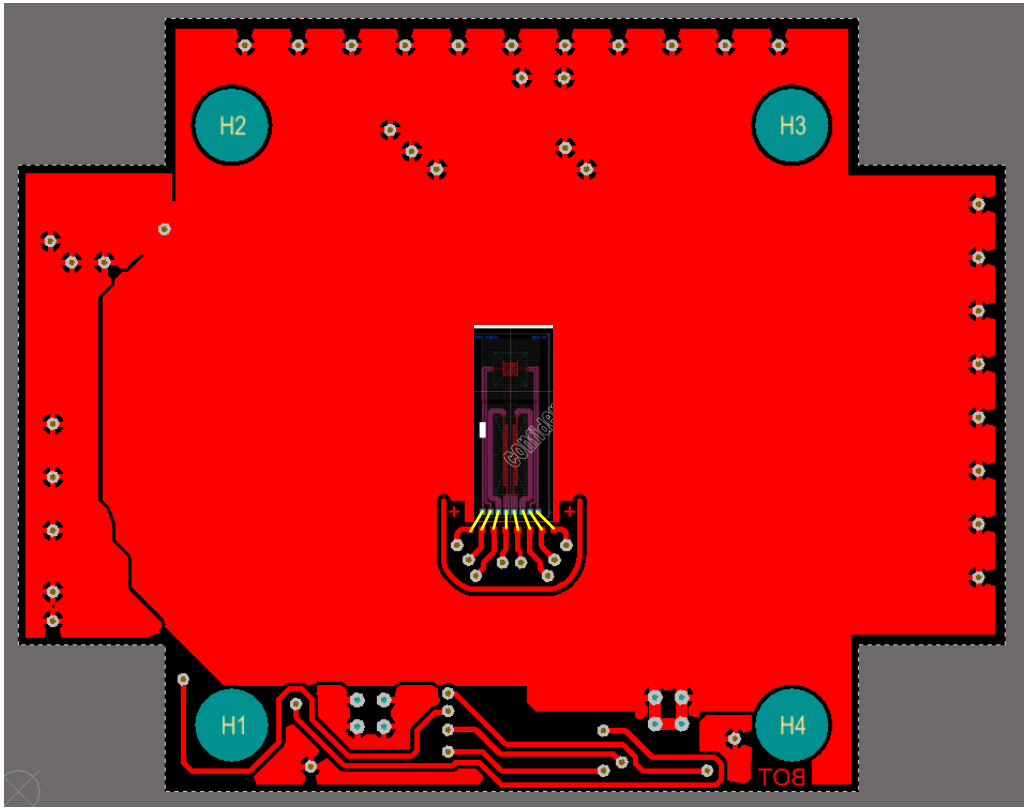
Sensitive Area DO NOT Handle Die From These Points

MEMS die information



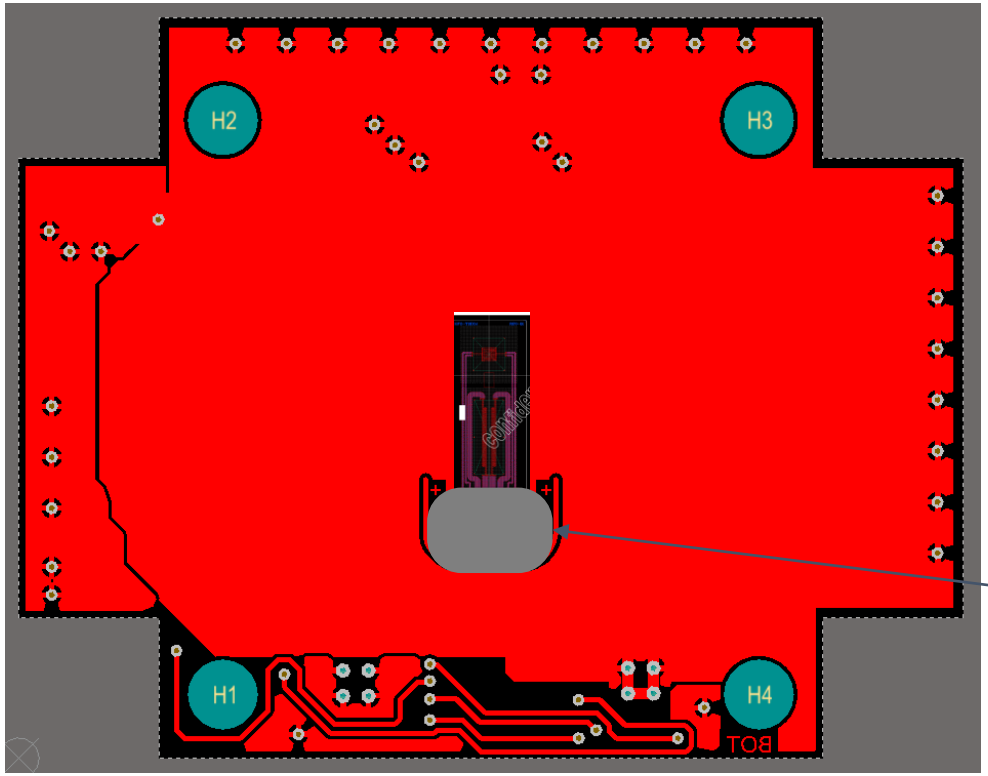
- PCB has recession on layer bottom.
- Die should be assembled inside this recession and the top side of the die should be inline with the gold PCB area
- Die Adhesive:
- Soft Silicon Type Adhesive such as Semicosil 989 or Similar

MEMS die information



- 8 Aluminum Wire Bond Pads on Chip Die 200x200 um each
- 8 Gold Platted Ni/Au bonds on PCB 200x200 um each
- 2 Gold Ball Bonds per Pad (Total 16 Wire Bonds per PCB)
- 25um Gold Wire to be Used
- Safe Bond Required per Each Bond

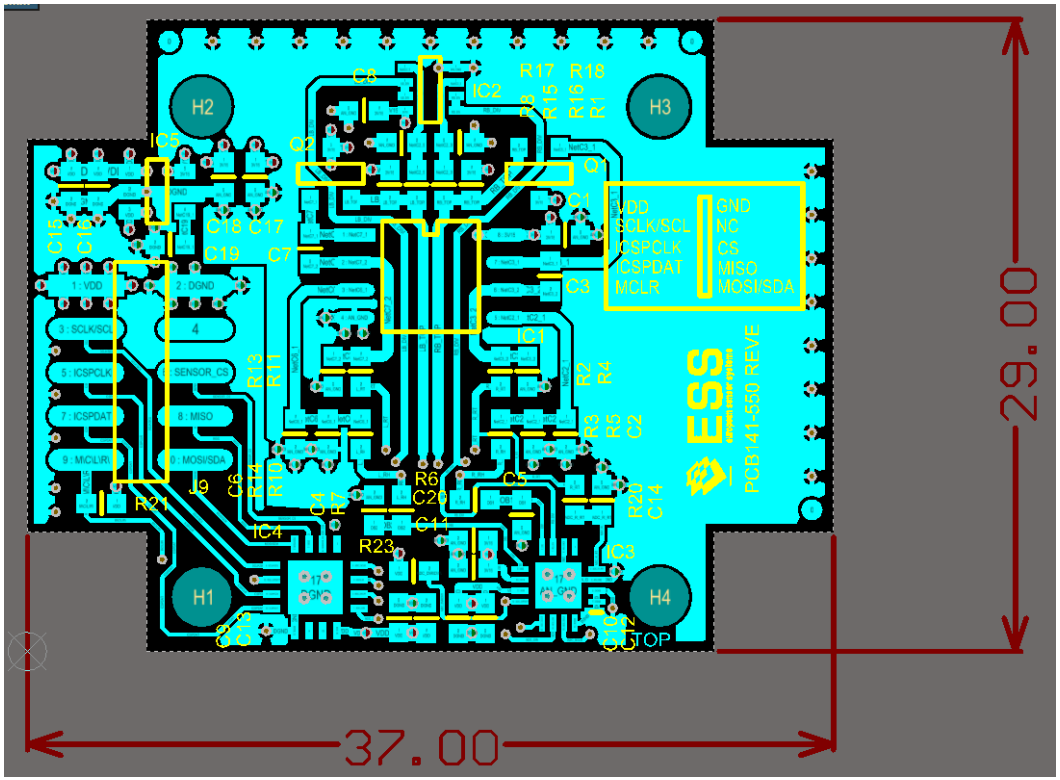
MEMS die information



- Wire Bonds should be covered uniformly by Glob Top
- Material Suggested: Stycast 50300 or Similar
- Glob Top Maximum Height: 1mm
- Glob Top Must NOT Touch Chip Die Sensitive Area
- Glob Tom must not exceed the marked contour area

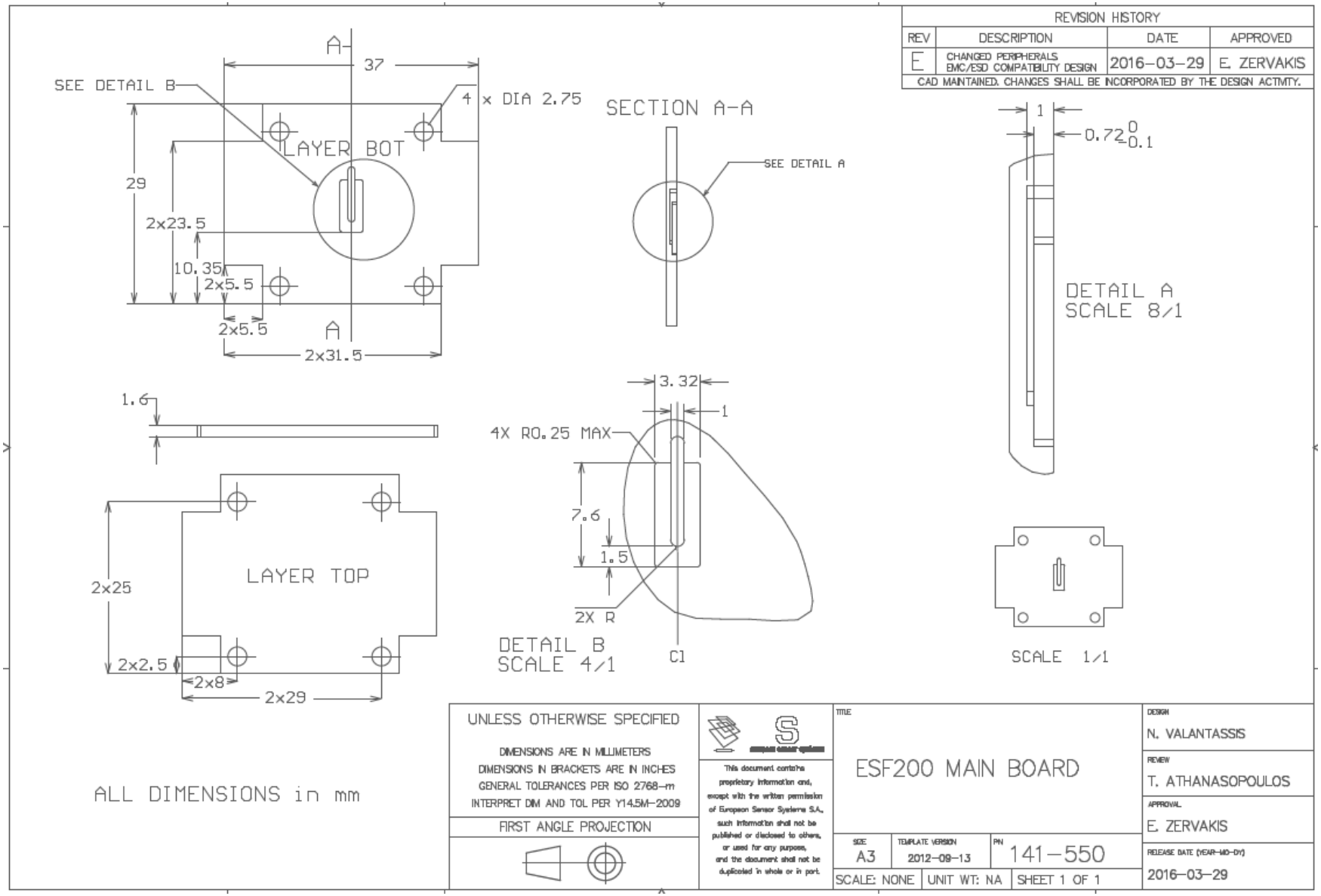
Glob Top Allowed Area

Electronic Component Assembly



- Opposite Side of PCB should be SMD assembled.
- ALL COMPONENTS COULD BE SUPPLIED BY ES Systems
- Process must be RoHS
- Dimensions in mm

Mechanical details



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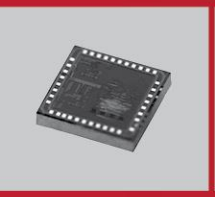
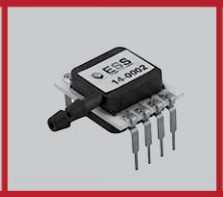

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